

TRANSPORTATION RAMM CHIPSEAL DATA

(to be completed for each seal layer on each road section)

SUBDIVISION	
ROAD NO / NAME	
CONTRACTOR	
START Mtr.	START DESCRIPTION
END Mtr.	END DESCRIPTION
WIDTH	DATE OF WORK
Seal Type	
Seal Reason	
Area Sealed (m²)	
Chip Grading (e.g. 3/5)	
Binder Type (e.g. B180/200)	
Chip Source Company	
Chip Source Quarry	
Total Volume of Binder Used	
(Litres)	
Temperature of Binder (°C)	
Residual Binder Rate (L/m²)	
Cutter (e.g. 3 pph Kero)	
Other Additives with concentrations	
(e.g. Polymer modification RS1, 3%)	

Surfacing Chip PSV testing form attached

Sealing Notes

(e.g. Weather, Temp)